

North America TC Chapter 3D Packaging & Integration (3DP&I) Global Technical Committee

Liaison Report | July 2021

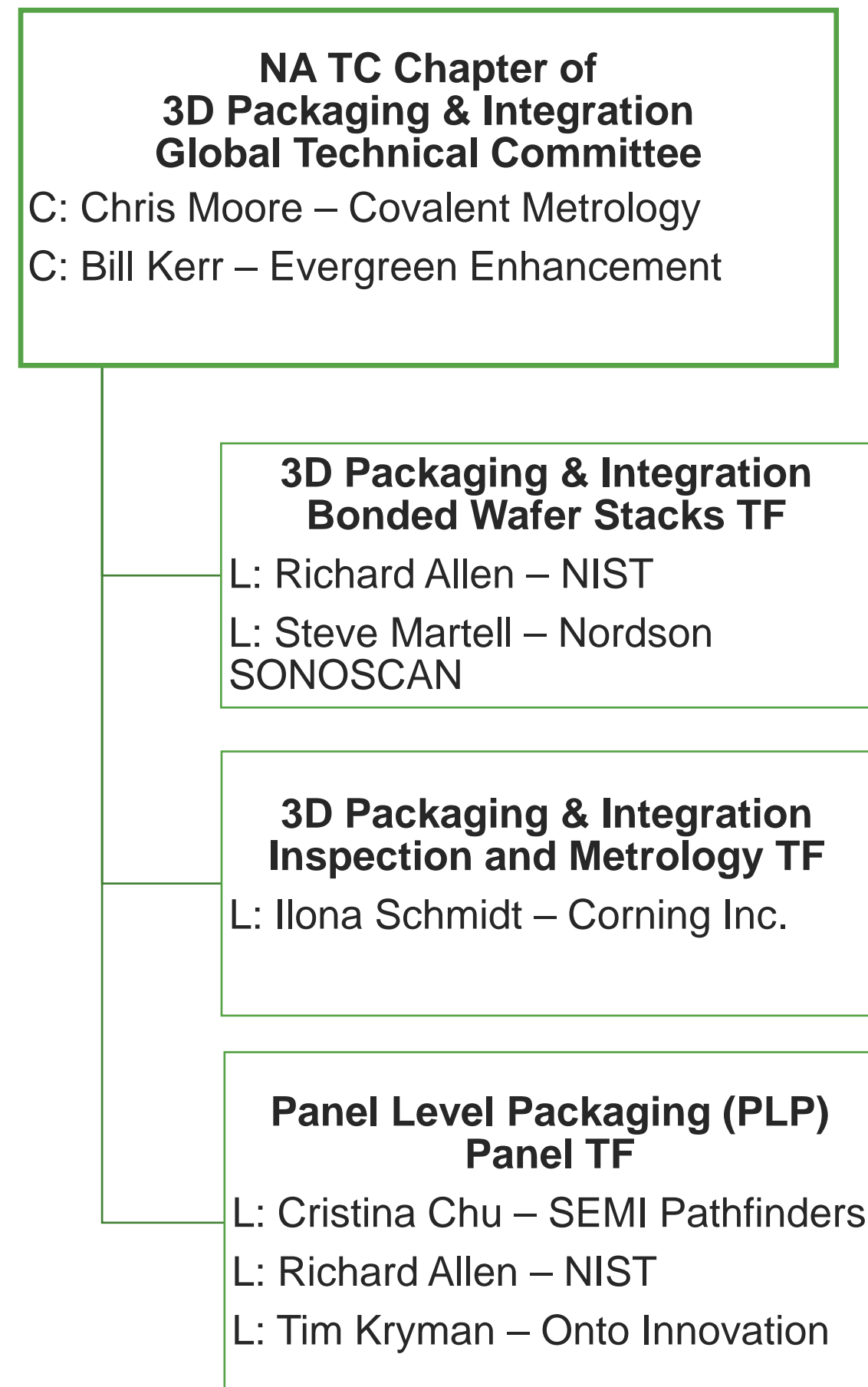
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Meeting Information

- Last meeting
 - Summer Meeting 2021
 - Thursday, July 15, 2021
 - via OVTCCM
- Next meeting
 - SEMICON West 2021
 - Schedule TBD

<http://www.semi.org/en/standards-events>

Organization Chart



Ballot Results [1/2]

Doc #	Document Title	TC Chapter Action
R6641	Revision to SEMI 3D8-0514, Guide for Describing Silicon Wafers for Use as 300 mm Carrier Wafers in a 3DS-IC Temporary Bond-Debond (TBDB) Process	Passed , A&R Cycle 7-2021
6810	Reapproval of SEMI 3D13-0715, Guide for Measuring Voids in Bonded Wafer Stacks	Passed , as balloted
6811	Reapproval of SEMI 3D2-0216, Specification for Glass Carrier Wafers for 3DS-IC Applications	Passed , as balloted
6812	Reapproval of SEMI 3D4-0915, Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks	Passed , as balloted

#1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Ballot Results [2/2]

Doc #	Document Title	TC Chapter Action
SEMI 3D13	SEMI 3D13-0715, Guide for Measuring Voids in Bonded Wafer Stacks <i>(Editorial Changes Type 2)</i>	Passed , to be submitted to ISC A&R SC
SEMI 3D2	SEMI 3D2-0216, Specification for Glass Carrier Wafers for 3DS-IC Applications <i>(Editorial Changes Type 2)</i>	Passed , to be submitted to ISC A&R SC
SEMI 3D4	SEMI 3D4-0915, Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks <i>(Editorial Changes Type 2)</i>	Passed , to be submitted to ISC A&R SC

#1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Authorized Activities

Doc #	Type	SC/TF/CFG	Document Title/Details
6829	SNARF	Bonded Wafer Stacks TF	Line Item Revision to SEMI 3D16-1116, Specification for Glass Base Material for Semiconductor Packaging

Note 1: SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsba1.nsf/TFOFSNARF>

Authorized Ballots

Doc #	Type	SC/TF/CFG	Document Title/Details
6829	Cycle 6 or 7-2021	Bonded Wafer Stacks TF	Line Item Revision to SEMI 3D16-1116, Specification for Glass Base Material for Semiconductor Packaging

Task Force Highlights



- Bonded Wafer Stacks TF and Inspection & Metrology TF met jointly
 - Reviewed Five-Year Review list and asked TC Chapter to authorize to ballot in Cycle 6 or 7-2021.
 - New topics for Fall 2021 meetings: cleaning of glass wafers, local flatness
- Panel Level Packaging (PLP) Panel TF
 - Reviewed SEMI 3D20, Specification for Panel Characteristics for Panel Level Packaging (PLP) Applications
 - TF met to discuss outcome of the SEMI 3D20 ballot
 - Target next TF meeting in 6-9 months
 - Will look at what optional parameters can be moved to Requirements section from Appendix 1

Thank you!

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